



Hysol[®] KS0001

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PRODUCT DESCRIPTION

Hysol[®] KS0001, conductive adhesive, is an economical electrically conductive epoxy paste. It is especially useful as a solder where heat cannot be tolerated since it cures at room temperature. The paste is useful as a repair for printed circuits, connect dissimilar metals, such as RF and corona shields, cementing leads and in other connecting and shielding problems. KS0001 is easy to handle with its simple mix ratio and 3 to 1 by or 7 to 3 by volume..

TYPICAL UNCURED PROPERTIES

Color	Part A	Gray
Specific Gravity @ 25°C	Part A	3.85
	Part B	3.20
Viscosity @ 25°C	Part A	Paste
	Part B	Paste
Shelf Life @ 25°C, from date of Manufacture, months	Part A	6
	Part B	6

TYPICAL CURED PROPERTIES

Color	Gray
Density, lb/cu in	0.133
Flammability	Pass
Specific Gravity	3.65
Tensile shear strength, Aluminum to aluminum, psi	1,600

TYPICAL CURED ELECTRICAL PROPERTIES

Volume Resistivity, ohm-cm	0.02
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HANDLING

Mix ratio, parts by weight	Part A / Part B	100/33
Mix ratio, parts by volume	Part A / Part B	7/3
Pot Life @ 25°C, 15 gram mass, minutes		60
Peak exotherm temperature		Negligible

CURE SCHEDULE

Recommended cure: 2 hours @ 60°C
 Alternate cure: 24 hours @ 25°C to handle, plus 24 hrs @ 25°C to ultimate properties

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

STORAGE

Liquid Storage – Liquids should be stored at 23°C or below, in closed containers. If stored below 23°C, the material MUST be allowed to come to room temperature, in the sealed container, to avoid moisture contamination.

DATA RANGES

The data contained herein may be reported as a typical value and/or range values based on actual test data and are verified on a periodic basis.

Note

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